

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE

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**Qi Specification version 2.0 –  
Part 10: MPP System Specification**

**Spécification Qi version 2.0 –  
Partie 10: Spécification du système MPP**



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Part 10: MPP System Specification

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### Part 10: MPP System Specification

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**Version 2.0**

**April 2023**

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